

# Effects of Length Dispersity and Film Fabrication on the Sheet Resistance of Copper Nanowire Transparent Conductors

James W. Borchert,<sup>a</sup> Ian E. Stewart,<sup>b</sup> Shengrong Ye,<sup>b</sup> Aaron R. Rathmell,<sup>b</sup> Benjamin J. Wiley,<sup>b</sup> and Karen I. Winey\*<sup>a</sup>

<sup>a</sup> Department of Materials Science and Engineering, University of Pennsylvania, Philadelphia, Pennsylvania 19104. Email: winey@seas.upenn.edu

<sup>b</sup> Department of Chemistry, Duke University, 124 Science Drive, Box 90354, Durham, North Carolina 27708, USA

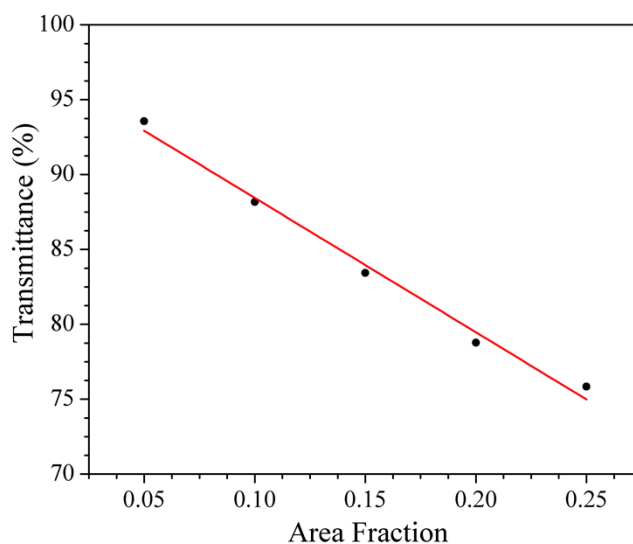


Figure S1: Calibration curve for the determination of Area Fraction from %T measurements of Cu NW films on PET. A linear fit was obtained using OriginPro 8.1. The fit details are as follows:

	Intercept		Slope		Statistics
	Value	Standard Error	Value	Standard Error	Adj. R-Square
%T	97.41234	0.84752	-89.71336	5.11071	0.98714